

10 9 8 7 6 5 4 3 2 1

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A



53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN: A0YAGI 2006/02/02 CHKD: YMAEDA 2006/02/03 APPR: NUKITA 2006/02/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY Y. A0YAGI	DATE 2006/01/30	TITLE 1.25 W-TO-B CONN. 51021,53261 MATING CROSS SECTION			
	10 OVER 30 UNDER	± ---	CHECKED BY Y. MAEDA	DATE 2006/01/30	MOLEX INCORPORATED			
	30 OVER	± ---	APPROVED BY N. UKITA	DATE 2006/01/30	MATERIAL NO. SEE CHART			
	ANGULAR ± --- °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DOCUMENT NO. SD-51021-002		SHEET NO. 1 OF 1	

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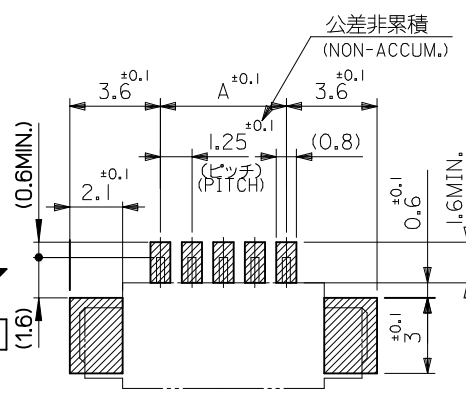
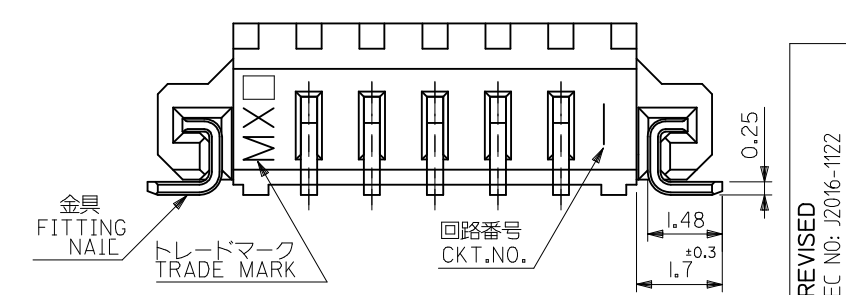
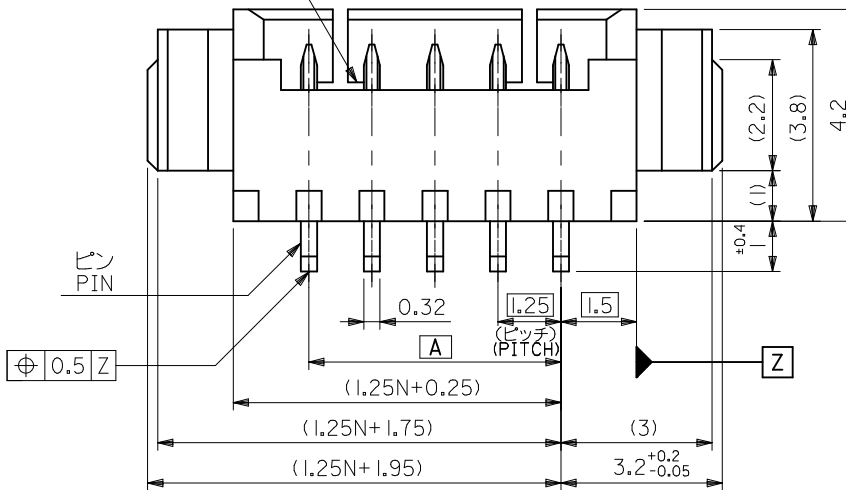
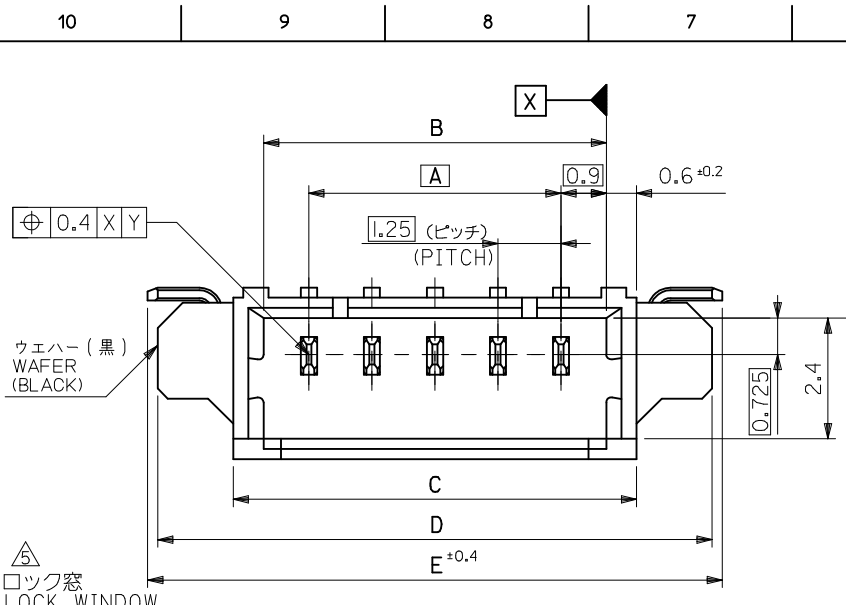
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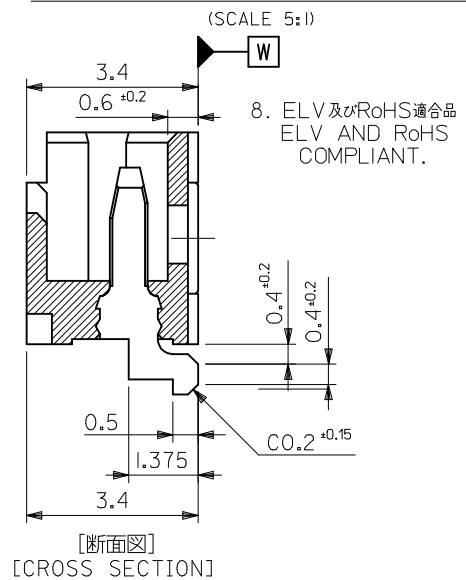
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参考基板レイアウト  
RECOMMENDED P.C.BOARD PATTERN DIM.(REF.)



【断面図】  
[CROSS SECTION]

注記 NOTES

- 嵌合相手: 51021 シリーズ  
MATES WITH: 51021 SERIES
- 材質  
MATERIAL  
ウエハー: NYLON 46, UL94V-0 GLASS FILLED 30%  
COLOR BLACK  
ピン: リン青銅  
PIN: PHOSPHOR BRONZE  
金具: リン青銅  
FITTING NAIL: PHOSPHOR BRONZE
- メッキ仕様  
PLATING  
ピン: 錫メッキ 1.0 μmMIN.  
PIN: TIN 1.0 MICROMETER MIN.  
下地メッキ: ニッケルメッキ 1.0 μmMIN.  
UNDER-PLATING: NICKEL 1.0 MICROMETER MIN.  
金具: 錫メッキ 1.0 μmMIN.  
FITTING NAIL: TIN 1.0 MICROMETER MIN.  
下地メッキ: ニッケルメッキ 1.0 μmMIN.  
UNDER-PLATING: NICKEL 1.0 MICROMETER MIN.
- ソルダーテール部のスレ量及び金具(補強板)のスレ量は基準面[W]に対し、上方向0.05MAX.、下方向に0.1MAX.とする。  
OFFSET BETWEEN BASIS PLANE [W] TO SOLDER TAIL BOTTOM AND FITTING NAIL BOTTOM:  
UPPER SIDE: 0.05MAX.  
LOWER SIDE: 0.1MAX.  
ロック窓は2、3極は1箇所、4極以上は2箇所とする。  
LOCK WINDOW: ONE PLACE FOR 2 AND 3 CKTS. AND TWO PLACES FOR MORE THAN 3 CKTS.
- 本製品は53261-\*\*11, -\*\*68の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 53261-\*\*11, -\*\*68.
- ソルダーテール及び金具の平坦度は0.1以下。  
SOLDER TAIL & FITTING NAIL COPLANARITY TO BE 0.1 MAX.

22.65	22.25	19.25	18.05	16.25	53261-1417	14
20.15	19.75	16.75	15.55	13.75	53261-1217	12
16.4	16	13	11.8	10	53261-0917	9
15.15	14.75	11.75	10.55	8.75	53261-0817	8
13.9	13.5	10.5	9.3	7.5	53261-0717	7
12.65	12.25	9.25	8.05	6.25	53261-0617	6
11.4	11	8	6.8	5	53261-0517	5
10.15	9.75	6.75	5.55	3.75	53261-0417	4
8.9	8.5	5.5	4.3	2.5	53261-0317	3
7.65	7.25	4.25	3.05	1.25	53261-0217	2

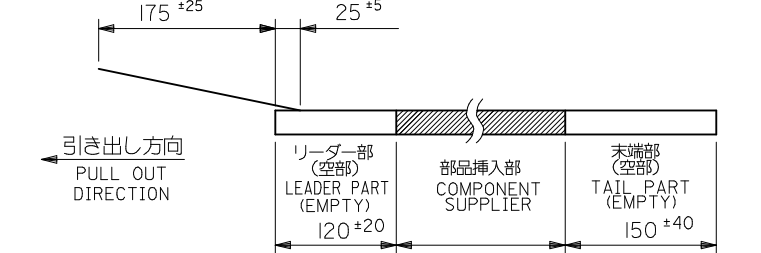
REVISED		EC NO: J2016-1122		2016/04/26		MODEL NO. 53261-**17	
G		DRWN: QHEJ1		2016/05/06		GENERAL TOLERANCES (UNLESS SPECIFIED)	
REV		CHKD: SAKIYAMA		2016/05/06		DIMENSION STYLE	
		APPR: IKANEKO		2016/05/06		MM ONLY	
						SCALE	
						10:1	
						DESIGN UNITS	
						METRIC	
						THIRD ANGLE PROJECTION	
						DRAWN BY	
						YWADA	
						DATE	
						04/04/12	
						CHECKED BY	
						MSASAO	
						DATE	
						04/04/12	
						APPROVED BY	
						MSASAO	
						DATE	
						04/04/12	
						MATERIAL NO.	
						SEE CHART	
						DOCUMENT NO.	
						SD-53261-025	
						SHEET NO.	
						1 OF 1	
						SIZE	
						A3	
						DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	
						THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

注記  
NOTES

1. 53261-\*\*-17 の詳細寸法については図面 SD-53261-025 を参照下さい。  
RE DETAILED DIMENSIONS,SEE SD-53261-025

2. 梱包数量：1000個/リール  
NUMBER OF CONNECTOR:1000PCS/REEL

3. リードテープ長さ LEAD TAPE LENGTH  
トップテープリーダ部 TOP TAPE LEADER PART 175<sup>+25</sup>  
トップテープ未接着部 TOP TAPE NON-BONDED PART 25<sup>+5</sup>



4. トップテープの剥離強度：0.1~1.3N {10 ~ 130gf} (剥離方向は下図参照)  
PEELING OFF FORCE OF TOP TAPE: 0.1~1.3N {10 ~ 130gf} (PEELING DIRECTION IS SHOWN IN FOLLOWING FIG.)

<剥離速度：300mm/min(参考)>  
PEELING SPEED:300mm/min. (REFERENCE)



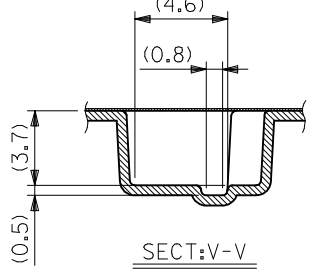
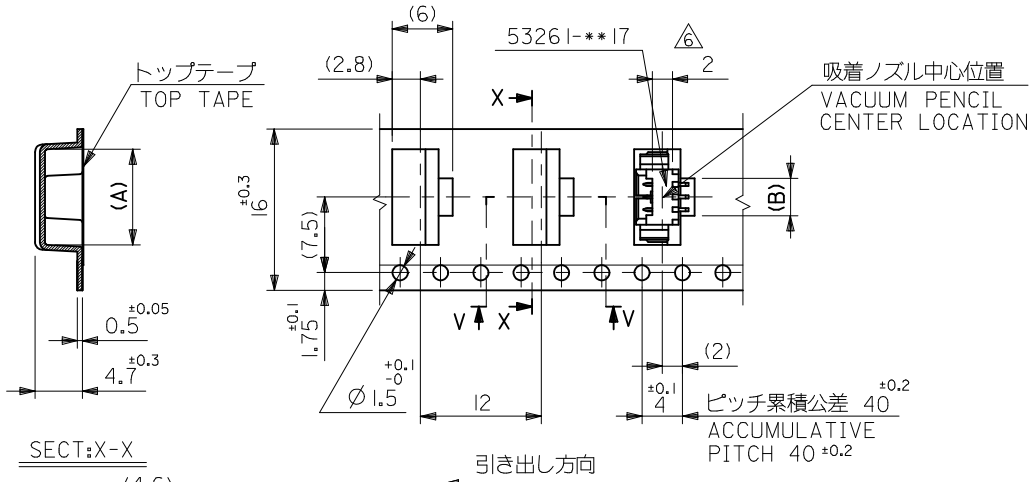
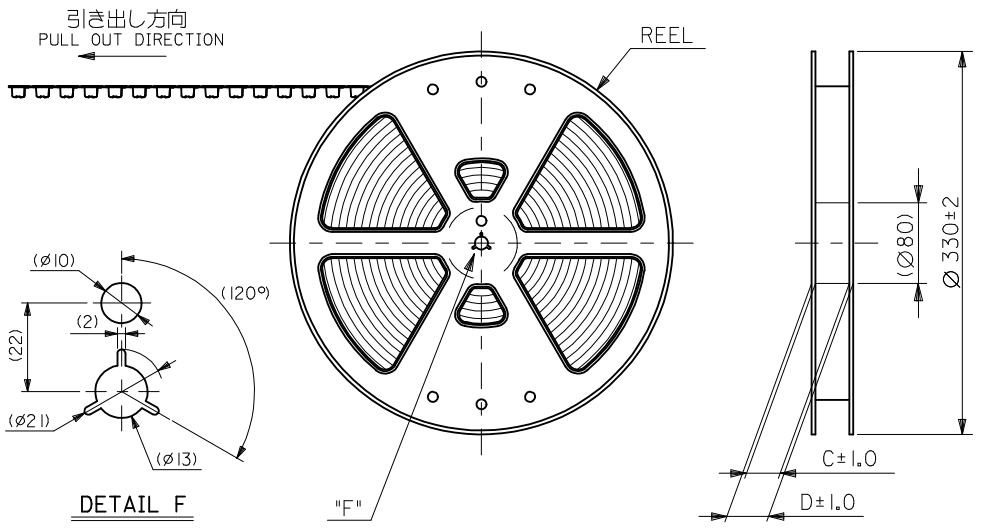
5. 材料 (MATERIAL)  
キャリアテープ(CARRIER TAPE):ポリプロピレン(POLYPROPYLENE)  
トップテープ (TOP TAPE): PET ,PE ,PEF  
リール (REEL):ポリスチレン (PS) <リサイクル材含む>  
POLYSTYRENE(PS) <RECYCLE MATERIAL CONTAINED>

△ コネクタ、ハウジング平面部  
CONNECTOR, HOUSING FLAT AREA

7. 本製品は53261-\*\*-95, -\*\*-98の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 53261-\*\*-95, -\*\*-98.

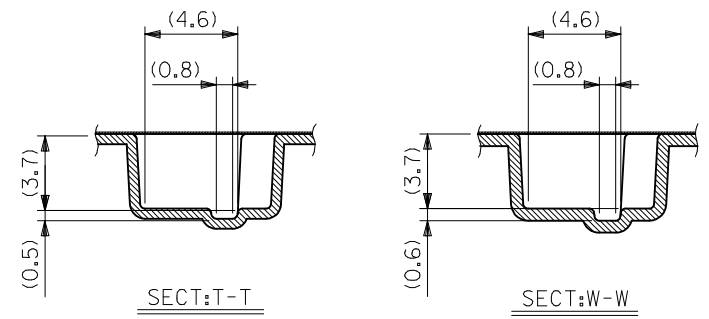
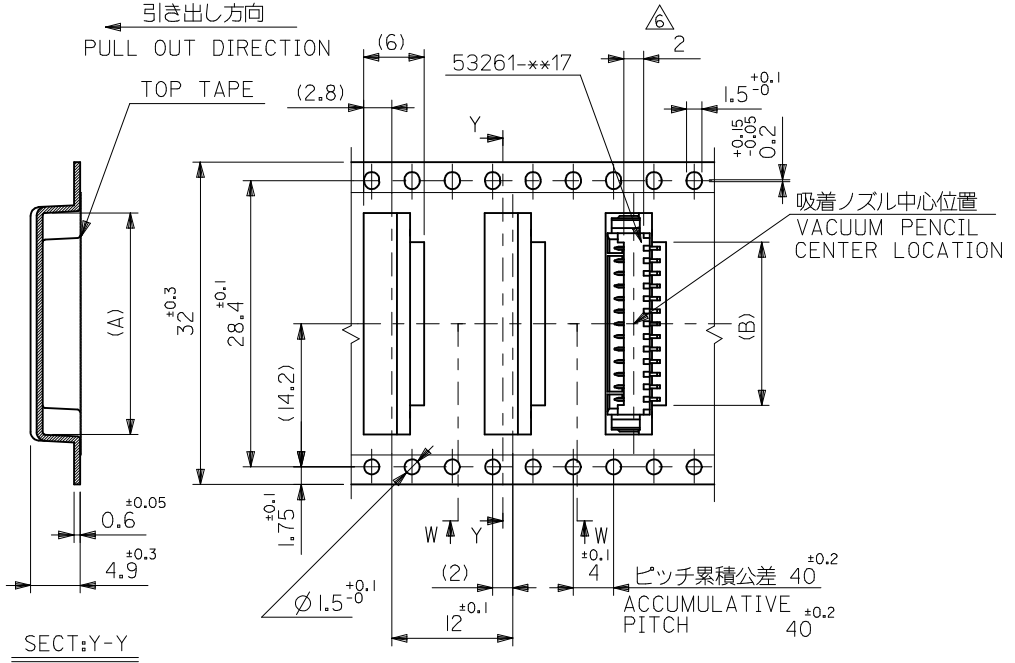
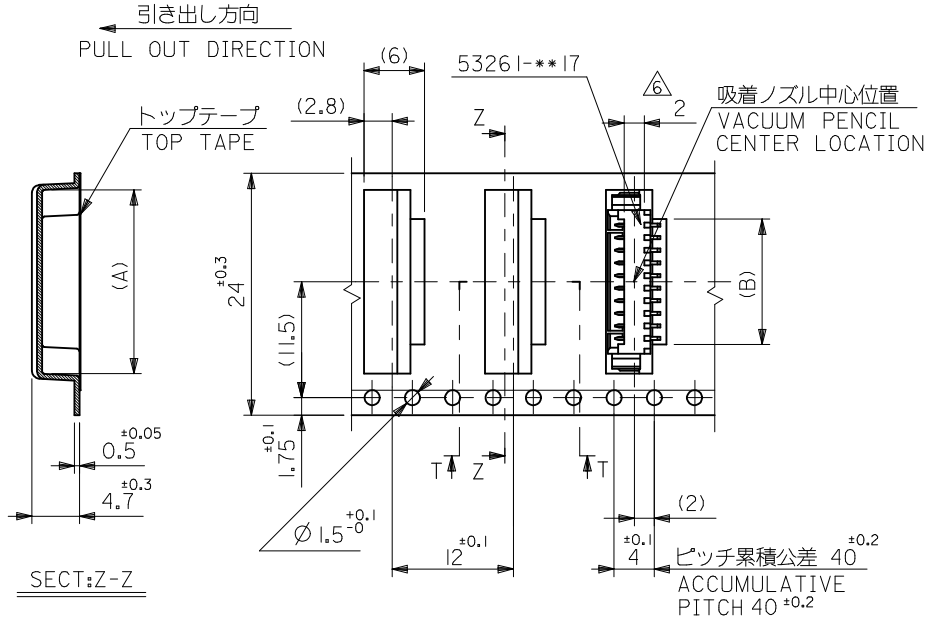
8. 本製品は乾燥剤入り、ハイバリア梱包品である。  
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

16	21.4	17.4	2.45	8.25	53261-0227	2
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	MATERIAL NO.	極数 CKT.
					MODEL NO.	53261-**-27



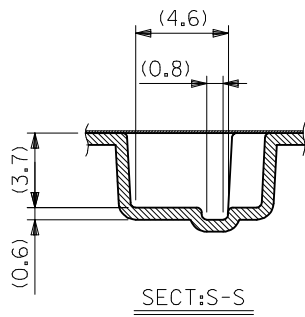
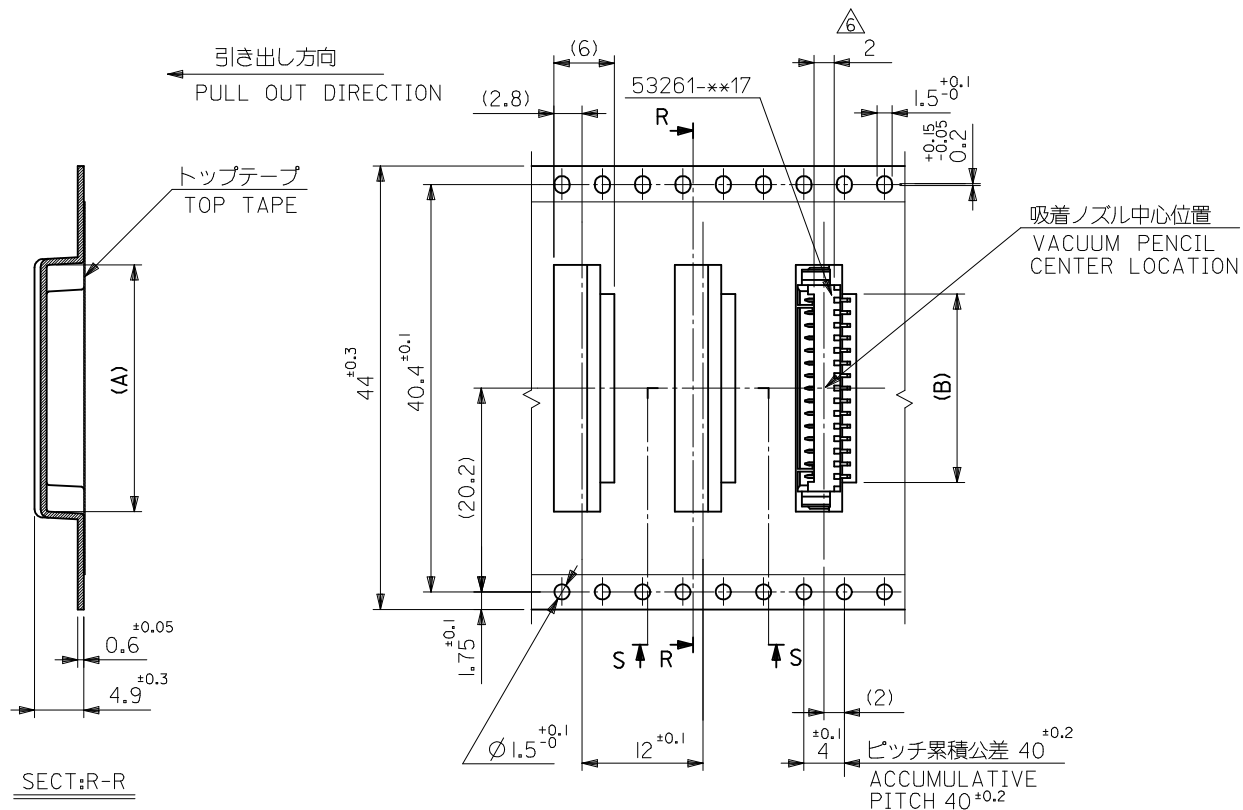
REVISED EC NO: J2009-2060 DRWN:TKON 2009/05/20 CHKD:HATSUMOTO 2009/05/21 APPR:NIKI ITA 2009/05/21	GENERAL TOLERANCES (UNLESS SPECIFIED)	
	10 UNDER	±0.2
	10 OVER 30 UNDER	±0.25
	30 OVER	±0.3
DESCRIPTION	ANGULAR	±3 °
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
DRAWN BY Y. WADA	DATE '04/04/12	TITLE 1.25 W/B CONN. WAFER ASSY SMT EMBSTP PKG -LEAD FREE-	
CHECKED BY M. SASAO	DATE '04/04/12	MOLEX INCORPORATED	
APPROVED BY M. SASAO	DATE '04/04/12	DOCUMENT NO. SD-53261-026	SHEET NO. 1 OF 3
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



32	37.4	33.4	14.95	20.75	53261-1227	12
24	29.4	25.4	11.2	17	53261-0927	9
			9.95	15.75	53261-0827	8
			8.7	14.5	53261-0727	7
			7.45	13.25	53261-0627	6
			6.2	12	53261-0527	5
			4.95	10.75	53261-0427	4
			3.7	9.5	53261-0327	3
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	MATERIAL NO.	極数 CKT.

REVISED EC NO: J2009-2060 DRWN:TKON 2009/05/20 CHKD:HATSUMOTO 2009/05/21 APPR:NUKITA 2009/05/21	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY	DATE	TITLE		
	10 OVER 30 UNDER	±0.25	Y. WADA	'04/04/12	1.25 W/B CONN. WAFER ASSY SMT EMBSTP PKG -LEAD FREE-		
	30 OVER	±0.3	M. SASAO	'04/04/12	MOLEX INCORPORATED		
	ANGULAR ±3 °	APPROVED BY	DATE	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	M. SASAO	'04/04/12	SEE CHART	SD-53261-026	2 OF 3	
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



44mm幅キャリアテープ  
44mm WIDTH CARRIER TAPE

44	49.5	45.4	17.45	23.25	53261-1427	14
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	MATERIAL NO.	極数 CKT.
					MODEL NO.	53261-**27

REVISED EC NO: J2009-2060 DRWN:TKON 2009/05/20 CHKD:HATSUMOTO 2009/05/21 APPR:NUKITA 2009/05/21 REV D	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		10 UNDER ±0.2	DRAWN BY Y. WADA	DATE '04/04/12	TITLE 1.25 W/B CONN. WAFER ASSY SMT EMBSTP PKG -LEAD FREE-	
		10 OVER 30 UNDER ±0.25	CHECKED BY M. SASAO	DATE '04/04/12	MOLEX INCORPORATED	
		30 OVER ±0.3	APPROVED BY M. SASAO	DATE '04/04/12	DOCUMENT NO. SD-53261-026	SHEET NO. 3 OF 3
		ANGULAR ±3 °	MATERIAL NO. SEE CHART	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE A3			